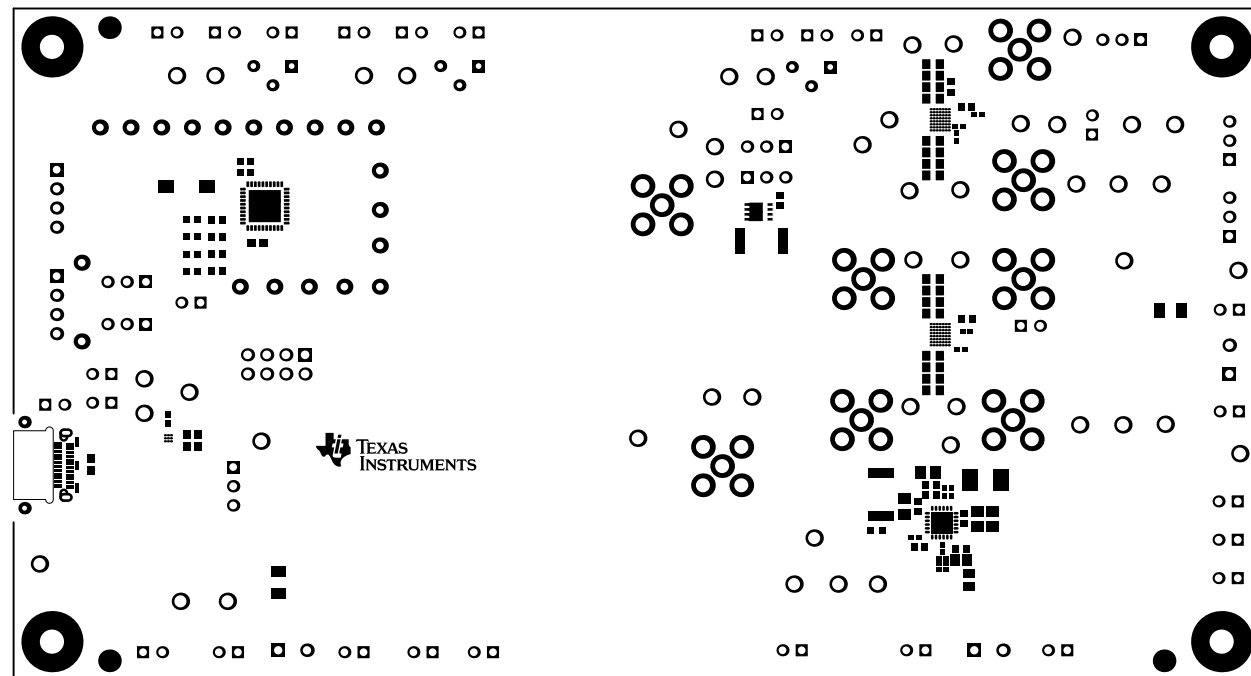
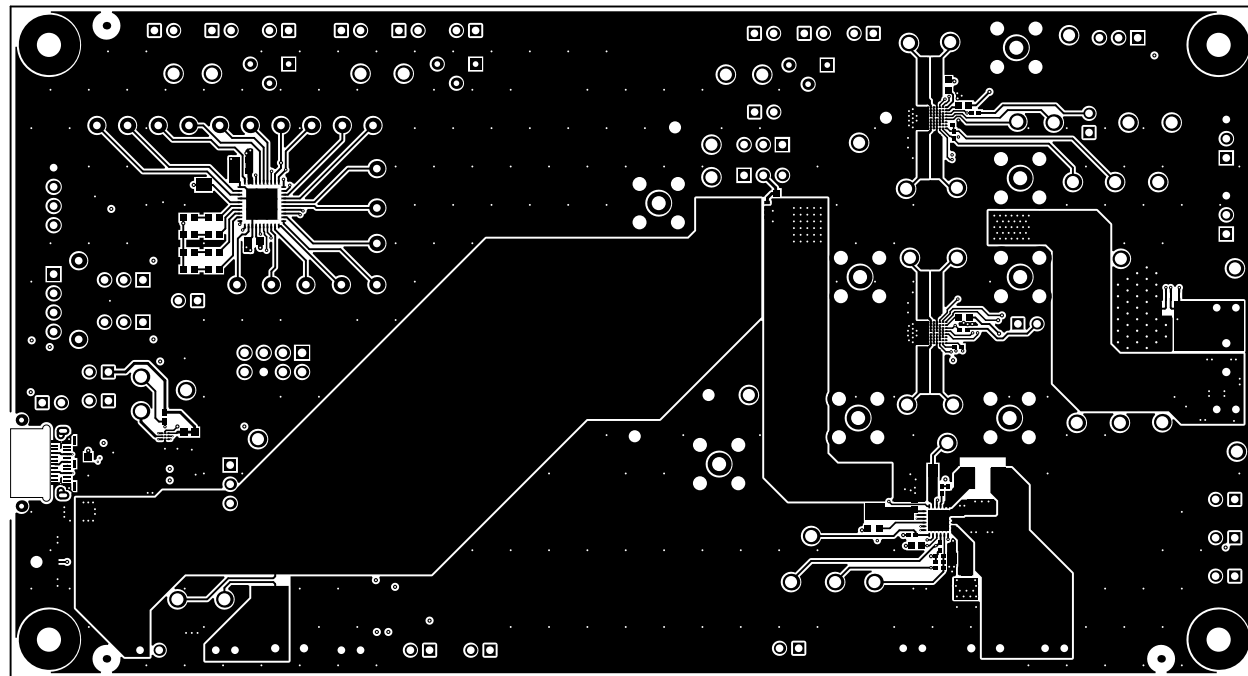


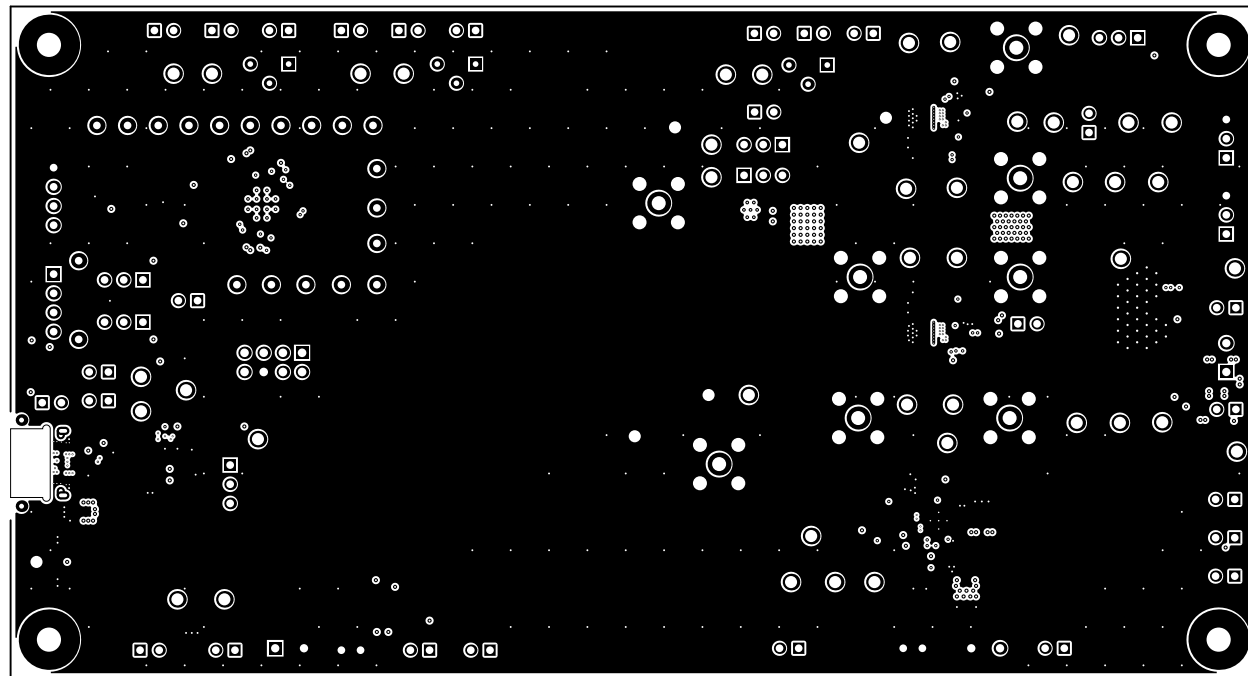
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 10/13/2017 2:00:41 PM	TEXAS INSTRUMENTS	



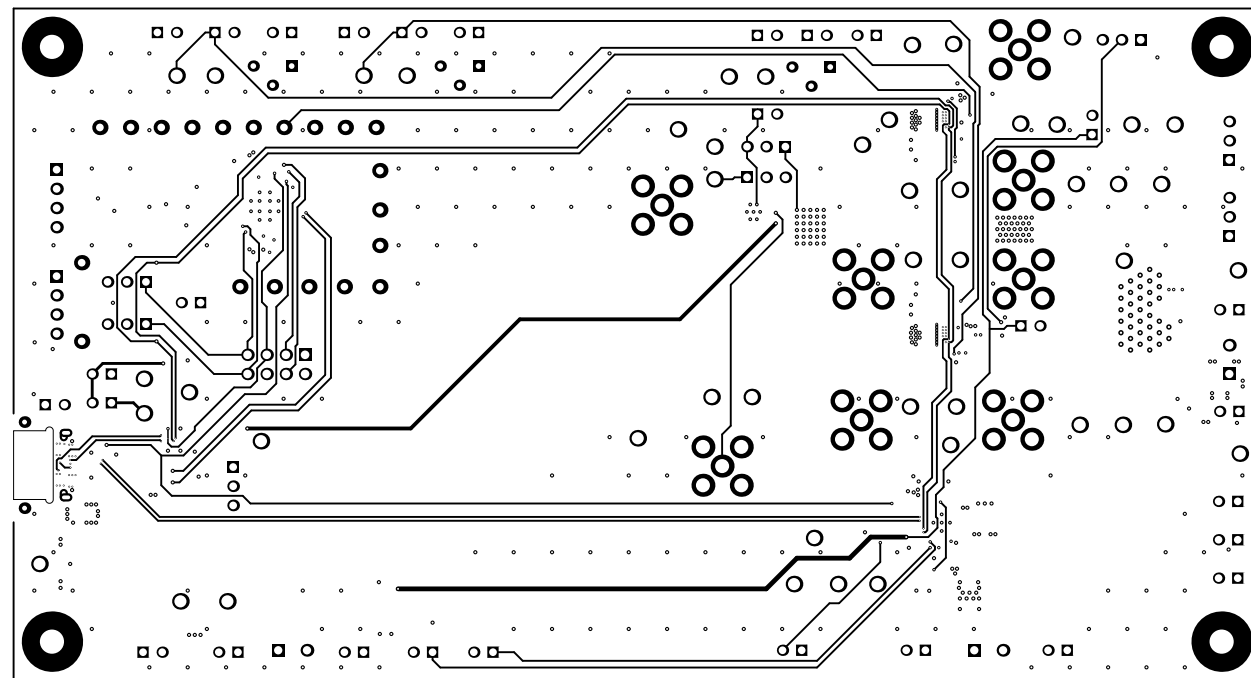
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 10/13/2017 2:00:42 PM	TEXAS INSTRUMENTS	



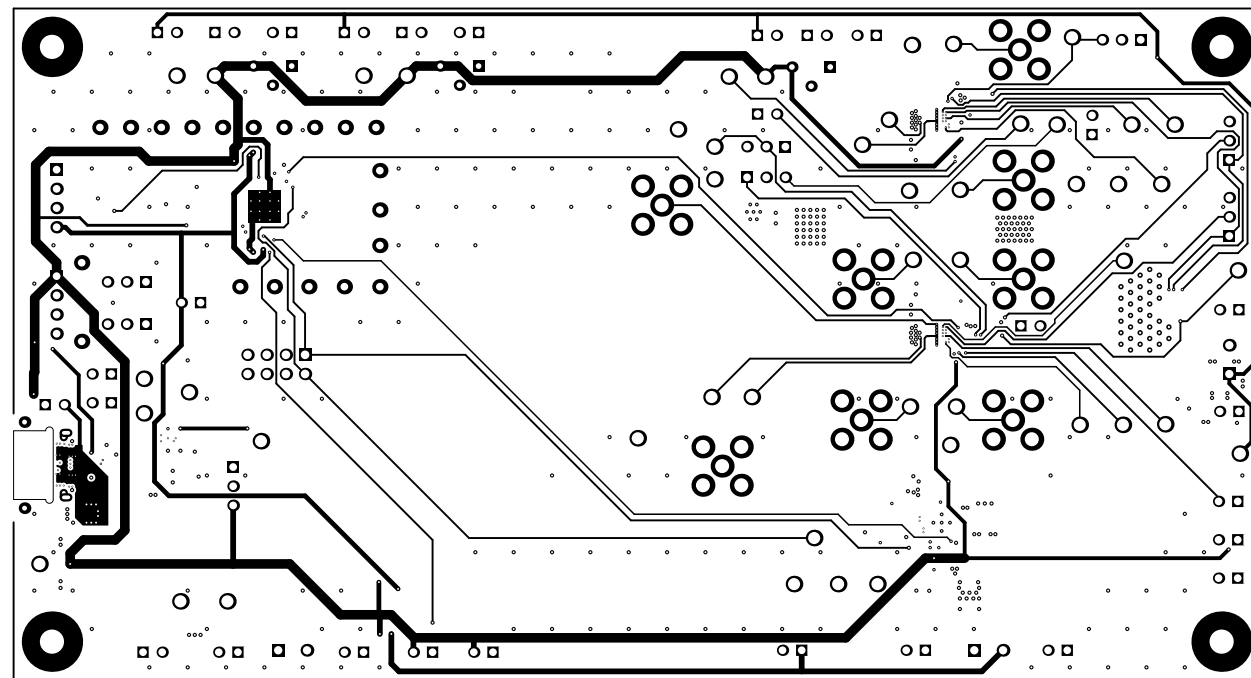
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 10/13/2017 2:00:43 PM	TEXAS INSTRUMENTS	



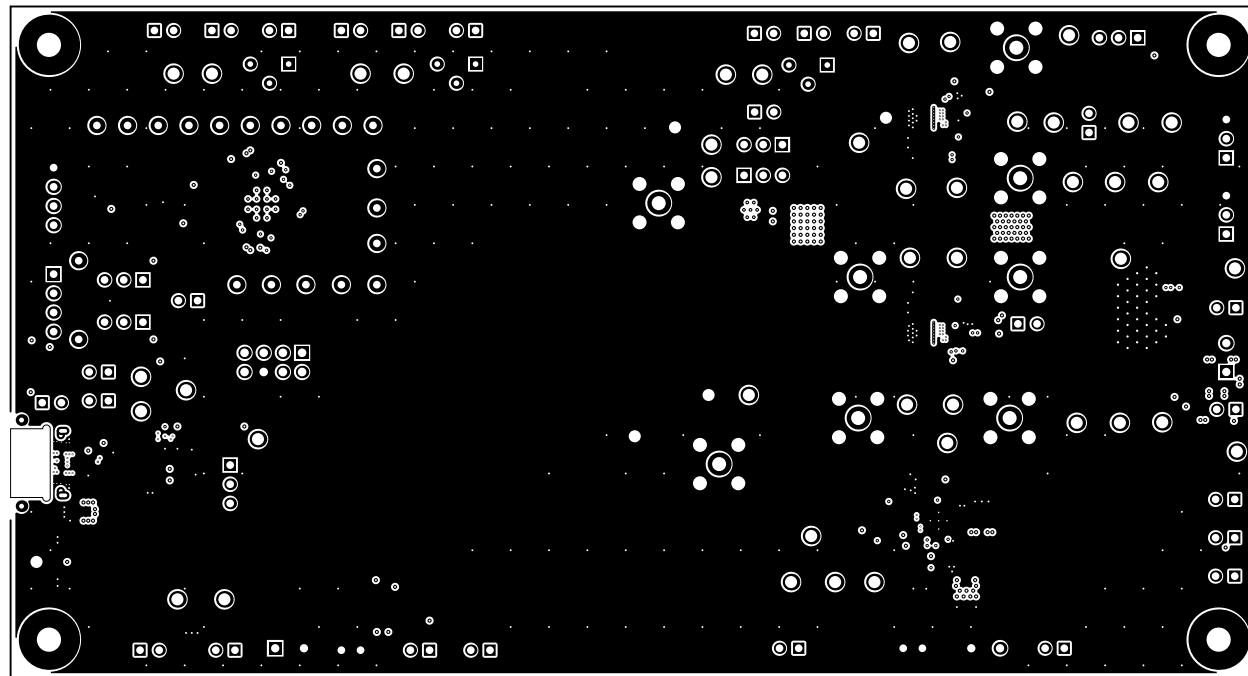
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 10/13/2017 2:00:43 PM	TEXAS INSTRUMENTS	



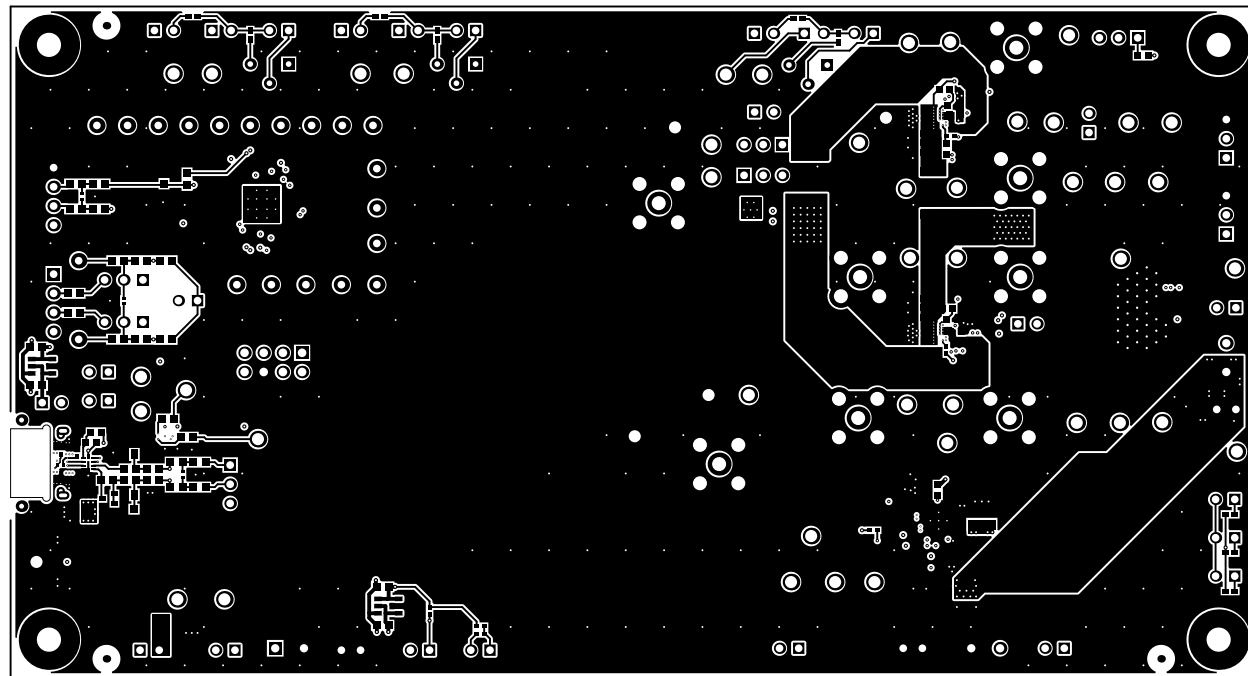
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 10/13/2017 2:00:44 PM	TEXAS INSTRUMENTS	



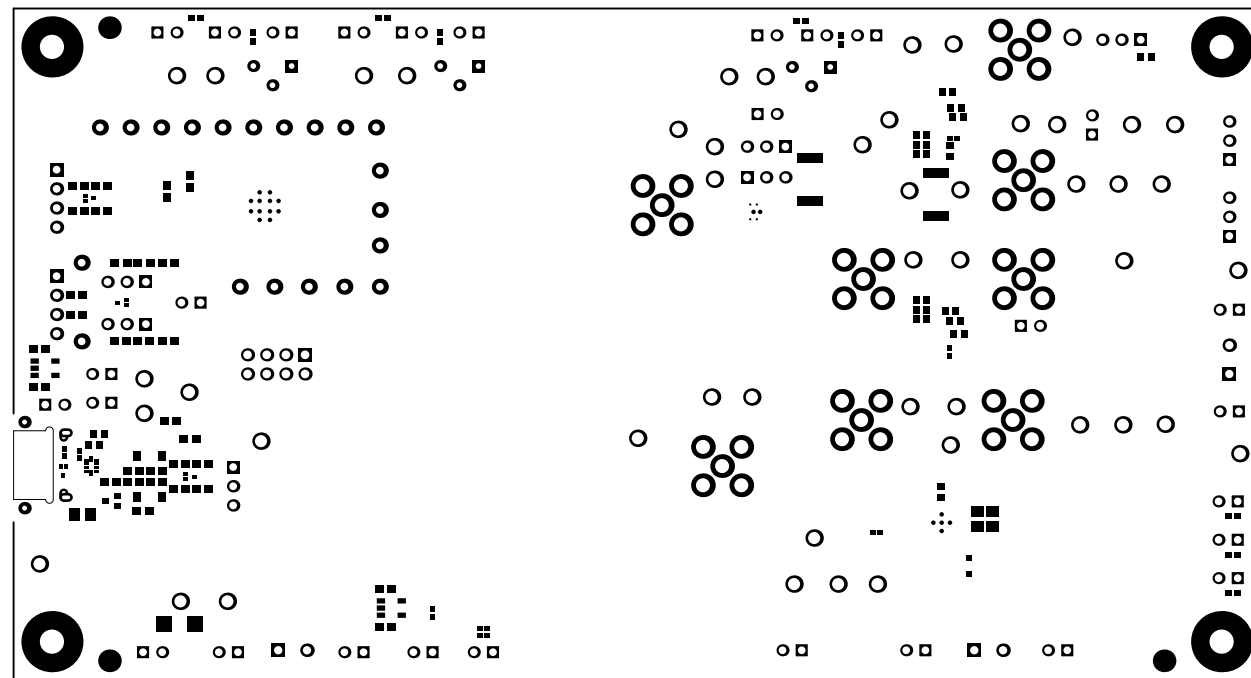
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3	TID #: N/A		
PLOT NAME = Signal Layer 3	GENERATED : 10/13/2017 2:00:45 PM	TEXAS INSTRUMENTS	



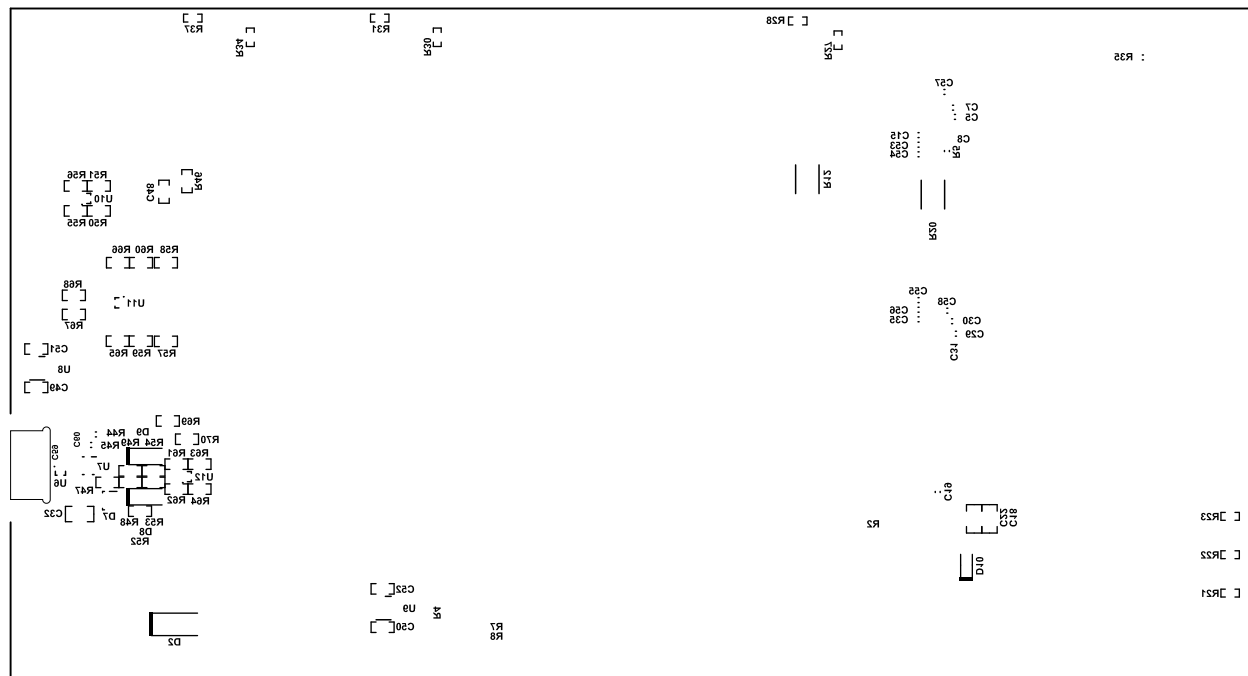
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 4	TID #: N/A		
PLOT NAME = Signal Layer 4	GENERATED : 10/13/2017 2:00:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 10/13/2017 2:00:46 PM	TEXAS INSTRUMENTS	



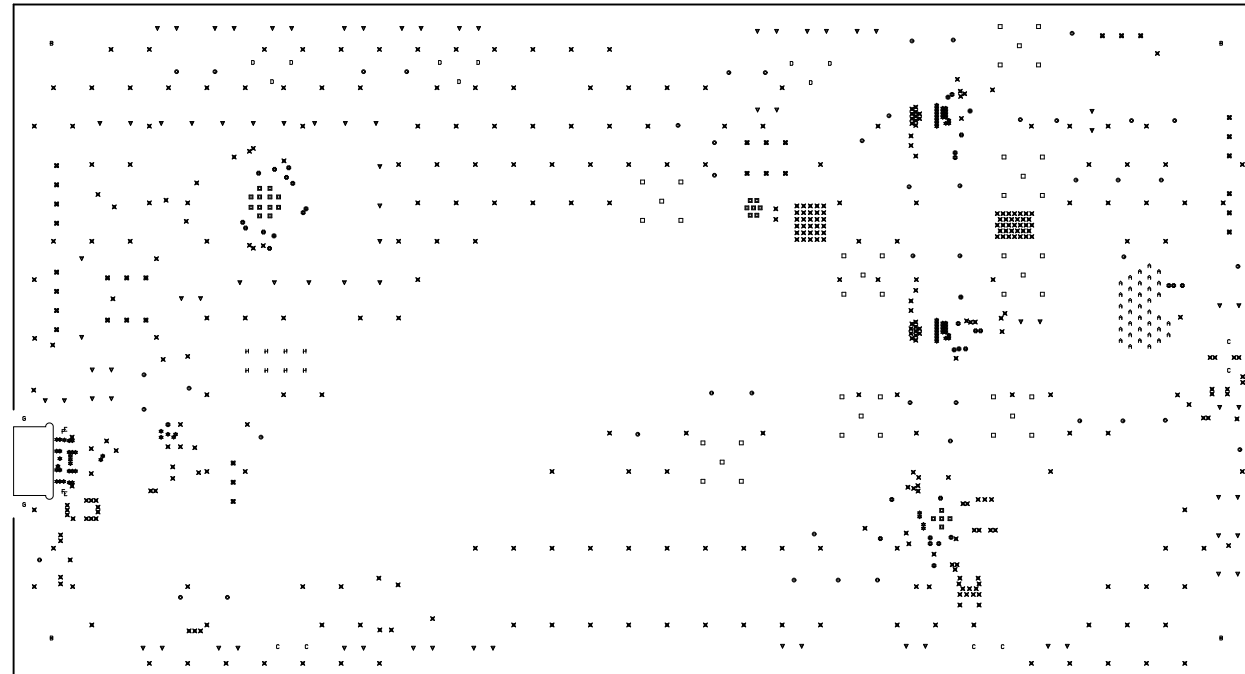
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/13/2017 2:00:47 PM	TEXAS INSTRUMENTS	



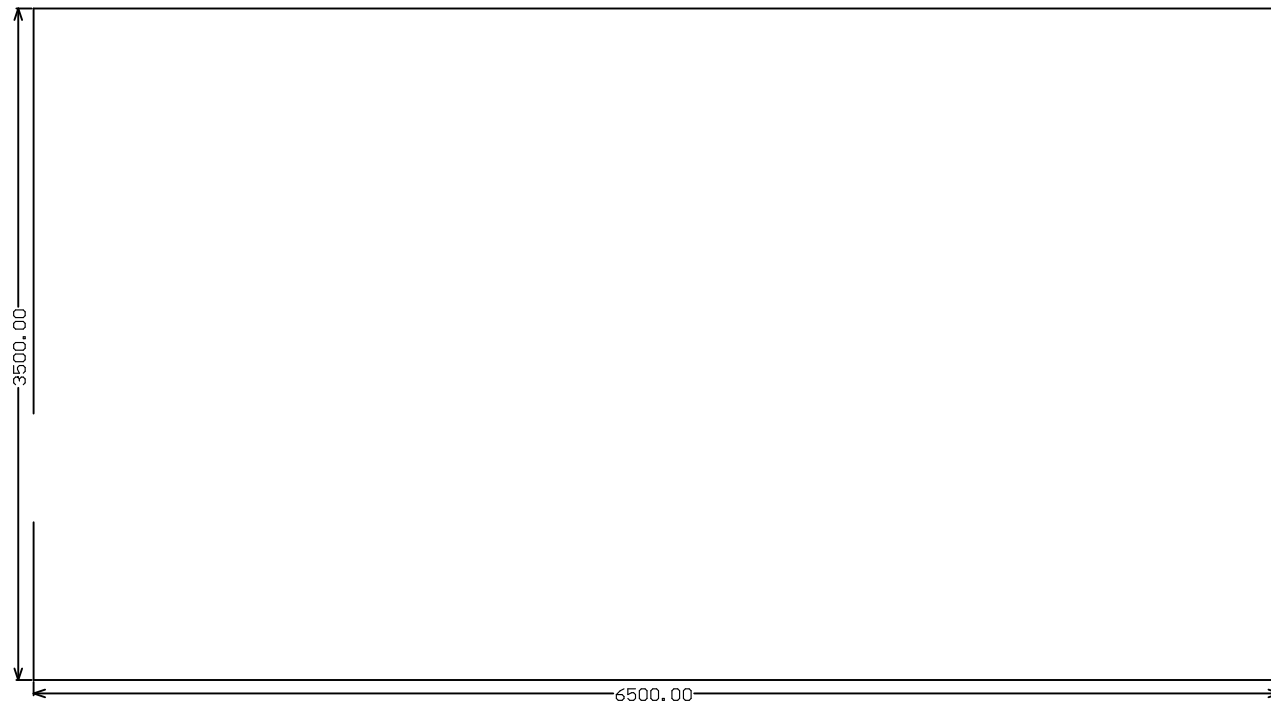
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 10/13/2017 2:00:48 PM	TEXAS INSTRUMENTS	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Hole Length	Routed Path Length
F	2	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r110_165h50_110r100	43.11mil (1.095mm)	23.43mil (0.595mm)
E	2	19.69mil (0.500mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r110_170h50_110r100	43.31mil (1.100mm)	23.62mil (0.600mm)
G	2	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c155h65	-	-
B	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c800h320	-	-
C	6	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
H	8	44.88mil (1.140mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
D	9	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
□	24	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	-	-
⊗	32	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
A	36	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v71h30m0mx0	-	-
⊕	37	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v46h20m0mx0	-	-
□	40	73.00mil (1.854mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c305h185	-	-
⊙	48	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c221h160	-	-
⊛	74	6.00mil (0.152mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	-	-
▽	78	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
⊗	399	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v56h25m0mx0	-	-
	801 Total									

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout
All 6 MIL-holed vias must be filled and plated over



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 10/13/2017 2:00:48 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR881	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 10/13/2017 2:00:51 PM	TEXAS INSTRUMENTS	

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